

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	80	"5323051"	USPAT; JPO	OR	ON	2005/05/12 23:18
L2	3	"6415505".pn. or "5925936".pn. or "6004867".pn.	USPAT; JPO	OR	ON	2005/05/12 23:20
L3	8	(257/777 or 438/108 or 438/109 or 361/760) and moveable near structures	USPAT; JPO	OR	ON	2005/05/12 23:30
L4	1374	(257/777 or 438/108 or 438/109 or 361/760) and lead with (ball or bump)	USPAT; JPO	OR	ON	2005/05/12 23:31
L5	582	(257/777) and lead with (ball or bump)	USPAT; JPO	OR	ON	2005/05/12 23:44
L7	0	"6522015".pn. and wir\$3 with instead with (ball or bump)	USPAT	OR	OFF	2005/05/12 23:38
L8	0	"6522015".pn. and wir\$3 with (instead or substitut\$3 or plac\$3) with (ball or bump)	USPAT	OR	OFF	2005/05/12 23:38
L9	13	(257/777) and wir\$3 with (instead or substitut\$3 or plac\$3) with (ball or bump) same lead	USPAT; JPO	OR	ON	2005/05/12 23:39
L10	32	mother near chip and lead with (ball or bump)	USPAT; JPO	OR	ON	2005/05/12 23:44
L11	0	"6239366".pn. and bump with (gold or "Ag")	USPAT	OR	OFF	2005/05/13 01:16
L12	0	"6239366".pn. and bump with (solder)	USPAT	OR	OFF	2005/05/13 01:16
L13	30	257/777 and lead same bump with (solder) and bump with (gold or "Ag")	USPAT	OR	OFF	2005/05/13 01:19
L14	17	257/777 and lead with flush	USPAT	OR	OFF	2005/05/13 01:25
L15	731	257/414	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 01:26
L16	923	257/415	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 01:40

L17	663	257/419	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 01:52
L18	2723	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 01:59
L19	3232	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 01:59
S1	1	"6046506".pn.	USPAT	OR	OFF	2005/05/11 20:40
S2	5	"6472239"	USPAT	OR	OFF	2005/05/12 14:08
S3	39	micromachine near (semiconductor or die or dice or chip or IC)	USPAT	OR	OFF	2005/05/12 14:09
S4	51	micromachine near (semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2005/05/12 14:09
S5	61	micromachine near (semiconductor or die or dice or chip or IC)	USPAT; JPO	OR	ON	2005/05/12 23:12